

## OAI MEMS TOOLS



The OAI Model 800 MBA Mask Aligner is a four-camera, manual, optical backside mask aligner system that is designed to greatly surpass the performance of IR backside aligners at an extremely competitive price.

#### APPLICATIONS

Excellent for MEMS, Microfluidics, Nano Imprint and Nanotechnology

Used for sub-micron printing and precise, level-to-level mask alignment

#### **FEATURES**

Four-camera optical system

Interchangeable mask holders & chucks

User-defined and controlled, substrateto-mask pressure

Non-contact, soft-contact and softthrough-hard vacuum contact capability

Precision chuck positioning

The Model 800 MBA provides full optical backside alignment and is ideal for use in R&D labs, universities, and low volume production. With the addition of available automation options, the MBA is suitable for higher rate production.

The Model 800 MBA may be purchased as a topside aligner and upgraded to full optical backside alignment capability when needed. This aligner can be configured with a wide variety of OAI lightsources that range in power up to 2KW and can accommodate substrates up to 8-inch square. The wafer chuck is positioned for very easy loading and unloading of the substrate. For added versatility, this aligner is available with an optional OAI Nano Imprint Module designed for NIL. OAI also offers a module designed for using liquid photoploymers for rapid prototyping or production of microfluidic devices.



Built on an anti-vibration table, the fixed mask holder assembly virtually guarantees alignment accuracy and repeatability. Using the Model 800 MBA is a simple process, as all functions are controlled via the easy to read LCD screens. An operator can be trained on the Model 800 MBA in a very short time and effectively learn to operate the tool in under one hour.



## **MORE FEATURES**

Up to 8" square substrate

Special small piece substrate holder

Sub-micron level-to-level alignment

High efficiency, uniform exposure system

Intensity controlled power supply

User definable operational parameters

Modular design

Motorized backside focus

Anti-vibration table

Dual video cameras with LCD screens

#### **BENEFITS**

Very versatile, front/backside optical alignment system

Cost effective tool that can be upgraded easily and affordably

Greatly exceeds IR system performance at a very competitive price

Fast changeover for masks and substrates

#### **AUTOMATION FEATURES**

Auto Z Positioning Chuck

Motorized auto leveling Auto gap setting

### **OPTIONS**

Electronic gap display

Electronic joy stick control\

Nano Imprint Module available

Microfluidic Module available

## GENERAL SPECIFICATIONS

# Front/Backside Mask Aligner System

**Mask rotation** Not required (camera compensation front/back)

Mask size Up to 9"x9"

**Mask loading** Vacuum and mechanical clamp

Mask/substrate separation Manual, user definable, infinitely variable

Mask/substrate pressure User definable

**Chuck motion control** X.Y.Z & Theta (differential micron)

0-3000µm **Exposure gap** 

**Gap adjustment** 1µm

**Mechanical resolution** 1.5µm

X. Y travel ±10mm

Theta travel **±4**°

Leveling Wedge-compensation system

Overlay accuracy Front to back <2µm (3s) - Top side to 0.5µm

Substrate size To 200mm square

**Printing modes Proximity, Soft, Hard & Vacuum Contact** 

**Printing resolution** Soft contact - 2µm

**Hard Contact Submicron** 

**Exposure time** 1-3.200 in 0.1 second increments



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